

## MAXIMUM RATINGS

Rating	Symbol	Value		Unit
Collector-Emitter Voltage MPQ6426 MPQ6427	V <sub>CEO</sub>	30 40		Vdc
Collector-Base Voltage MPQ6426 MPQ6427	V <sub>CBO</sub>	40 50		Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	12		Vdc
Collector Current — Continuous	I <sub>C</sub>	500		mAdc
		Each Die	Four Die Equal Power	
Total Device Dissipation @ T <sub>A</sub> = 25°C(1) Derate above 25°C	P <sub>D</sub>	500 4.0	900 7.2	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	825 6.7	2400 19.2	mW mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150		°C

(1) Second Breakdown occurs at power levels greater than 3 times the power dissipation rating.

## THERMAL CHARACTERISTICS

Characteristic		Junction to Case	Junction to Ambient	Unit
Thermal Resistance	Each Die	151	250	°C/W
	Effective, 4 Die	52	139	°C/W
Coupling Factors	Q1-Q4 or Q2-Q3	34	70	%
	Q1-Q2 or Q3-Q4	2.0	26	%

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
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### OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage(2) (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0)	MPQ6426 MPQ6427	V <sub>(BR)CEO</sub>	30 40	—	Vdc
Collector-Base Breakdown Voltage (I <sub>C</sub> = 100 μAdc, I <sub>E</sub> = 0)	MPQ6426 MPQ6427	V <sub>(BR)CBO</sub>	40 50	—	Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 10 μAdc, I <sub>C</sub> = 0)		V <sub>(BR)EBO</sub>	12	—	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 30 Vdc, I <sub>E</sub> = 0)		I <sub>CBO</sub>	—	100	nAdc
Emitter Cutoff Current (V <sub>BE</sub> = 10 Vdc, I <sub>C</sub> = 0)		I <sub>EBO</sub>	—	100	nAdc

### ON CHARACTERISTICS(2)

DC Current Gain (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 Vdc) (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 5.0 Vdc)		h <sub>FE</sub>	5000 10,000	—	—
Collector-Emitter Saturation Voltage (I <sub>C</sub> = 100 mAdc, I <sub>B</sub> = 0.1 mAdc)		V <sub>CE(sat)</sub>	—	1.5	Vdc
Base-Emitter On Voltage (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 5.0 Vdc)		V <sub>BE(on)</sub>	—	2.0	Vdc

### SMALL-SIGNAL CHARACTERISTICS

Current-Gain — Bandwidth Product (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 5.0 Vdc, f = 100 MHz)		f <sub>T</sub>	125	—	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 100 kHz)		C <sub>obo</sub>	—	8.0	pF
Input Capacitance (V <sub>BE</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 100 kHz)		C <sub>ibo</sub>	—	15	pF

(2) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

# MPQ6426 MPQ6427

CASE 646-05, STYLE 1  
TO-116

QUAD  
DARLINGTON TRANSISTOR

NPN SILICON

**NOISE CHARACTERISTICS**  
( $V_{CE} = 5.0 \text{ Vdc}$ ,  $T_A = 25^\circ\text{C}$ )

FIGURE 1 – NOISE VOLTAGE

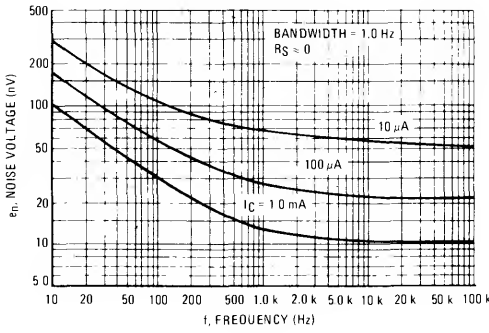


FIGURE 2 – NOISE CURRENT

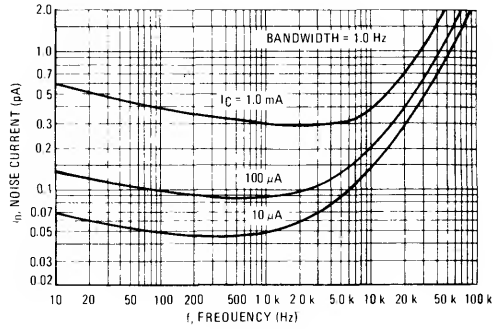


FIGURE 3 – TOTAL WIDEBAND NOISE VOLTAGE

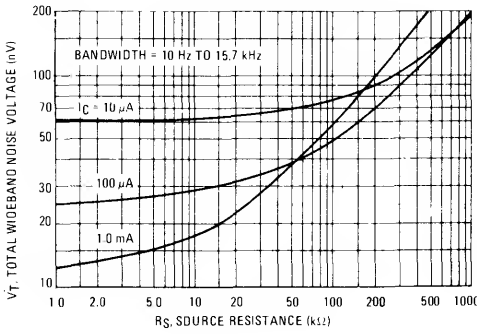
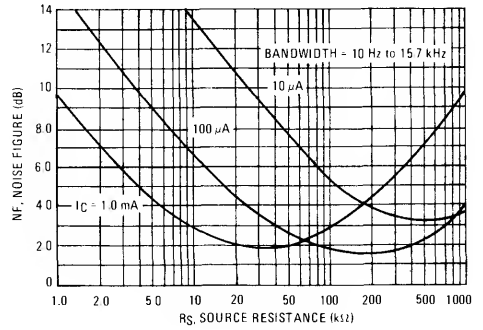


FIGURE 4 – WIDEBAND NOISE FIGURE



**DYNAMIC CHARACTERISTICS**

FIGURE 5 – CAPACITANCE

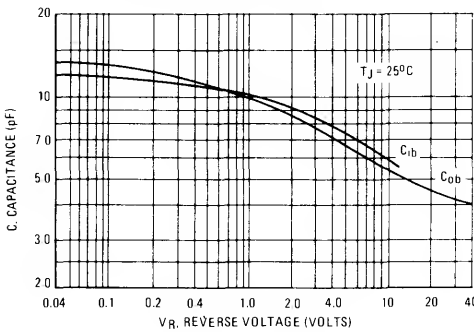
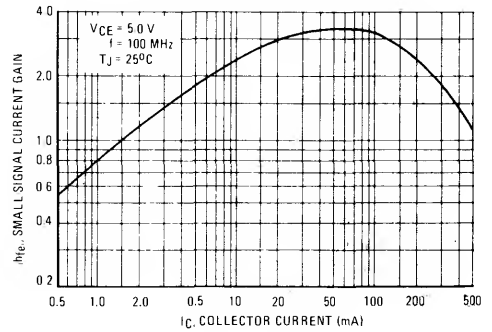


FIGURE 6 – HIGH FREQUENCY CURRENT GAIN



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